





NPN SILICON PLANAR HIGH VOLTAGE TRANSISTOR PowerDI®5

Features

- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 2.8W
- V_{CEO} = 400V
- I_C = 300mA; I_{CM} = 1A
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Applications

- PSU start up switch
- Telecom switch

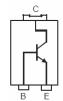
Mechanical Data

- Case: PowerDI[®]5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 63
- Weight: 0.093 grams (approximate)









Top View

Bottom View

Device Schematic

Pin-out diagram

Ordering Information (Note 3)

Part Number	Case	Packaging
DXT458P5-13	PowerDI [®] 5	5000/Tape & Reel

Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



DXT458 = Product Type Marking Code

Oli = Manufacturers' Code Marking

K = Factory Designator

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 09 for 2009)

WW = Week code (01 to 53)





Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	400	V
Collector-Emitter Voltage	V _{CEO}	400	V
Emitter-Base Voltage	V _{EBO}	5	V
Continuous Collector Current	Ic	300	mA
Base Current	Ι _Β	200	mA
Peak Pulse Current	I _{CM}	1	A

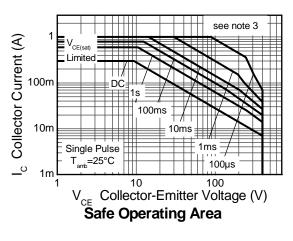
Thermal Characteristics

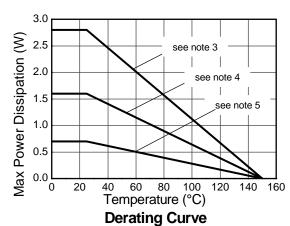
Characteristic	Symbol	Value	Unit
Power Dissipation @ T _A = 25°C (Note 4)	P_{D}	2.8	W
Thermal Resistance, Junction to Ambient Air (Note 4) @T _A = 25°C	$R_{ hetaJA}$	45	°C/W
Power Dissipation @ T _A = 25°C (Note 5)	P_{D}	1.3	W
Thermal Resistance, Junction to Ambient Air (Note 5) @T _A = 25°C	$R_{ hetaJA}$	96	°C/W
Power Dissipation @ T _A = 25°C (Note 6)	P_{D}	0.7	W
Thermal Resistance, Junction to Ambient Air (Note 6) @T _A = 25°C	$R_{ hetaJA}$	179	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ hetaJT}$	14	°C/W
Operating and Storage Temperature Range	T_J , T_{STG}	-55 to +150	°C

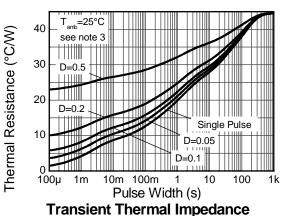
Notes:

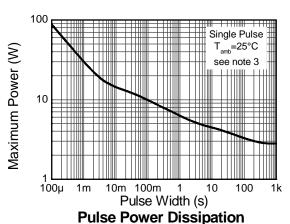
- 4. Device mounted on 1.6mm FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
- 5. Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
- 6. Device mounted on 1.6mm FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.















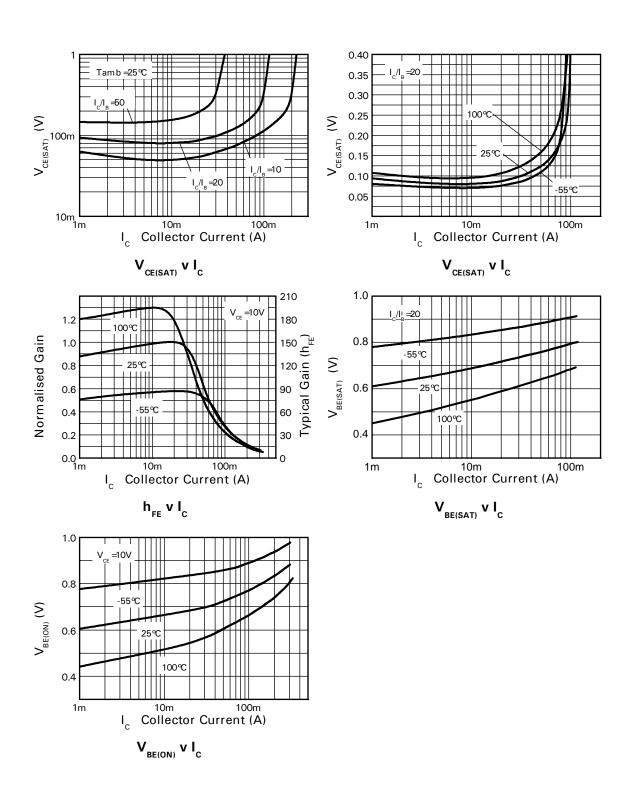
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	400	_	-	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 7)	V _{CEO(sus)}	400	_	-	V	I _C = 10mA
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	5	_	-	V	$I_E = 100 \mu A$
Collector Cutoff Current	I _{CBO}	-	_	100	nA	V _{CB} = 320V
Collector Cutoff Current	I _{CES}		_	100	nA	V _{CB} = 320V
Emitter Cutoff Current	I _{EBO}	-	_	100	nA	V _{EB} = 4V
Collector-Emitter Saturation Voltage (Note 7)	V	-	_	200	mV	$I_C = 20\text{mA}$, $I_B = 2\text{mA}$
Collector-Emitter Saturation voltage (Note 7)	V _{CE(sat)}	-	-	500	IIIV	$I_C = 50$ mA, $I_B = 6$ mA
Base-Emitter Saturation Voltage (Note 7)	V _{BE(sat)}	ı	-	900	mV	$I_C = 50 \text{mA}, I_B = 5 \text{mA}$
Base-Emitter Turn-On Voltage (Note 7)	V _{BE(on)}	Î	_	900	mV	$V_{CE} = 10V$, $I_C = 50mA$
	h _{FE}	100	_	=		$V_{CE} = 10V$, $I_C = 1mA$
C Current Gain (Note 7)		100	_	300	_	$V_{CE} = 10V$, $I_C = 50mA$
		15	-	-		$V_{CE} = 10V, I_{C} = 100mA$
ansition Frequency	f⊤	50	_		MHz	$V_{CE} = 20V, I_{C} = 10mA,$
	''	00			1711 12	f = 20MHz
Output Capacitance	C_{obo}	-	-	5	pF	$V_{CB} = 20V, f = 1MHz$
Switching Times	t _{on}	-	135	-	ı ns i	$V_{CC} = 100V, I_C = 50mA,$
itching filles	t _{off}	-	2260	_		$I_{B1} = 5mA$, $I_{B2} = 10mA$

7. Pulse Test: Pulse width ≤300µs. Duty cycle ≤2.0%. Notes:

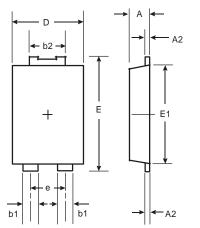


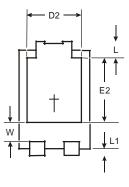
Typical Characteristic





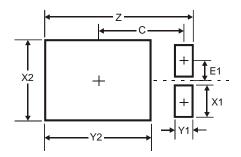
Package Outline Dimensions





	PowerDI [®] 5				
Dim	Min	Max			
Α	1.05	1.15			
A2	0.33	0.43			
b1	0.80	0.99			
b2	1.70	1.88			
D	3.90	4.05			
D2	3.054 Typ				
Е	6.40	6.60			
е	1.84	Тур			
E1	5.30	5.45			
E2	3.549 Typ				
L	0.75	0.95			
L1	0.50	0.65			
W	1.10	1.41			
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
С	3.87
F1	0.9





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